

## Attachment No. 2

### Minutes of the CE-2.9 Subcommittee on Sockets 24 –25 April 2006 Ft. Lauderdale, FL

Facilitator Carl Fritz welcomed everyone, and said that the meeting would be conducted following the published agenda.

#### 1. Approval of the 17 – 18 October 2005 Minutes

1. The minutes of the 17 – 18 October 2006 meeting in Memphis, TN was approved. Moved by John Healey and seconded by Ralph Antonelli. The motion was unanimously moved and approved.

#### 2. SPECIFICATIONS BY PROJECT NUMBERS

A. SP-4965: Rev. EIA-540B0AE: Detail Land Grid Array (Contech Research is sponsor)

To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

B. SP-4970: EIA-540DAAA-A: Detail, DIP

It was reported that the specification is at EDEC for approval.

C. SP-4971: EIA-700A0AB: 68-pin Memory Card Connector

It was reported that the specification is at EDEC for approval.

D. SP-4973: EIA-540B0AB: Low Pin Count BGA

To be reviewed when EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets is developed.

E. SP-4982-1: EIA-5400000A: Generic

It was reported that the standard was sent to EIA for processing and is awaiting EDEC approval. It was noted that Max Peel did not accept the committee's response to his rejection when he returned the purple rejection card. The committee moved by Bob Druckenmiller and seconded by Ralph Antonelli to override Max Peel's objection and approve the previous action to reaffirm the specification, and publish as a reaffirmed ANSI standard. The members present approved the motion, with Carl Fritz casting a negative vote.

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F. SP-4983: EIA-540BAAA-A: Detail, Mechanically Actuated PGA (Contech Research is the sponsor)

Carl Fritz reported that the project was cancelled 18 April 2006.

G. SP-5055: Replacement document for EIA-676 Detail, SFF 1.8 inch (45.7 mm) Disk Drives

It was reported that there were 2 approvals and 3 abstentions received by EIA. It was sent to EIA for processing and is awaiting EDEC approval. EIA indicated that it needs committee approval to go to EDEC due to lack of sufficient ballots at the April 2006 meeting. It was moved by Bob Druckenmiller and seconded by Frank Ruffino to approved the specification and send to EIA for EDEC ballot and publication as an ANSI specification. This action was unanimously approved at this meeting due to lack of sufficient ballots. The agenda clearly indicated that: "If any SP listed below receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting."

H. SP-5056: EIA-674: Detail, SFF 1.8" Disk Drives

Carl Fritz reported that this specification was sent to EIA for EDEC ballot on 10 October 2005. There were 2 approvals and 2 abstentions, and 1 approved ballot with comments, approved by the committee, from Harvey Waltersdorf received by EIA. EIA indicated that it needs committee approval to go to EDEC due to lack of sufficient ballots at the April 2006 meeting. It was moved by Bob Druckenmiller and seconded by Frank Ruffino to approved the specification and send to EIA for EDEC ballot and publication as an ANSI specification. This action was unanimously approved at this meeting due to lack of sufficient ballots. The agenda clearly indicated that: "If any SP listed below receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting."

I. SP-5058-A: EIA-720: Detail, SFF 2.5" Disk Drives

It was reported that there were 4 approvals and 3 abstentions received by EIA as of 20 April 2006. It was moved by John Healey and seconded by Ralph Antonelli to send to EIA for EDEC ballot, and publication as an ANSI specification, if there are no rejections or negative comments are received by the ballot expiration date of 29 May 2006. The motion was unanimously approved.

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### J. SP-5059: EIA-677: Detail, SFF Power Connector Pin Dimensions

It was reported that there were 5 approvals ballots received and no comments. It was sent to EIA for processing and is awaiting EDEC approval. EIA indicated that it needs committee approval to go to EDEC due to lack of sufficient ballots at the April 2006 meeting. It was moved by Bob Druckenmiller and seconded by Frank Ruffino to approved the specification and send to EIA for EDEC ballot and publication as an ANSI specification. This action was unanimously approved at this meeting due to lack of sufficient ballots. The agenda clearly indicated that: "If any SP listed below receives insufficient votes for approval, the committee may approve the document for EDEC ballot at this meeting."

### K. SP-5112 as follows:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

It was reported that the standard was sent to EIA for processing and is awaiting EDEC approval. It was noted that Max Peel did not accepted the committee's response to his rejection when he returned the purple rejection card. The committee moved by Bob Druckenmiller and seconded by Ralph Antonelli to override Max Peel's objection and approve the previous action to reaffirm the specification, and publish as a reaffirmed ANSI standard. The members present approved the motion, with Carl Fritz casting a negative vote.

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L. SP-5114 as follows:

- 540C000: Sectional Relay Sockets
- 540CA00: Blank, Relay Sockets
- 540CAAA: Detail, 10A Relay Socket
- 540CAAB: Detail, 5A Relay Socket

It was reported that the standard was sent to EIA for processing and is awaiting EDEC approval. It was noted that Max Peel did not accept the committee's response to his rejection when he returned the purple rejection card. The committee moved by Bob Druckenmiller and seconded by Ralph Antonelli to override Max Peel's objection and approve the previous action to reaffirm the specification, and publish as a reaffirmed ANSI standard. The members present approved the motion, with Carl Fritz casting a negative vote.

### 3. SPECIFICATIONS AWAITING PROJECT NUMBERS

A. EIA-364-1003, Ball Grid Array (BGA) and Land Grid Array (LGA) Test Sequence for Electrical Connectors and Sockets (Contech Research, Tom Peel)

The following concerns were raised by John Healey at the last meeting:

1. Is this document only designed for one piece connector or socket where by the mating half is a processor module?
2. Why are socket design features included in this standard?
3. Try and make this standard look as much like the EIA-364-1000.01 standard from a format perspective.

A consensus poll of the committee members supported the concerns expressed by John Healey on items 2 and 3.

Carl Fritz reported that the specification is still under development.

### 4. NEW BUSINESS

There was no new business.

Prepared by  
Carl Fritz, Facilitator, CE-2.9